

LISTING OF THE CLAIMS

1-7. (Cancelled).

8. (Previously Presented) A device for sorting wafers stored in cassettes comprising:

a housing;

a wafer handling device arranged in a chamber configured to be sealed off with respect to the housing, wherein the wafer-handling device accesses a measuring station;

a part for receiving at least two closable cassettes arranged in the housing and separated from said chamber by a partition, said part configured to position a received cassette against a closable opening in said partition, wherein through opening of said closable opening said closable cassette is opened and placed in communication with said chamber so that said wafer handling device can remove wafers from the cassette or position them therein;

a store for closable cassettes arranged in the housing; and

a handling device for closable cassettes arranged in the housing, wherein the store for closable cassettes and the handling device for closable cassettes are separated from the part for receiving at least two cassettes, and wherein the wafer-handling device is adapted to transfer the wafers directly between cassettes in a sorting function.

9. (Previously Presented) The device of Claim 8, wherein the device is configured for sorting wafers stored in FOUPs.

10. (Canceled)

11. (Previously Presented) The device of Claim 8, wherein the part for receiving at least two cassettes comprises a turntable.

12. (Previously Presented) The device of Claim 8, wherein the store for cassettes comprises a rotatable magazine.

13. (Previously Presented) A method for assembling a batch of wafers in cassettes comprising the steps of:

placing at least a first and a second closed cassette in a store;

employing a cassette handling device to select and move the first cassette from the store to a sorting operation, wherein the first cassette is opened and placed in active connection with a wafer handling device in a chamber;

employing a cassette handling device to select and move a second cassette from the store to a sorting operation, wherein the second cassette is opened and placed in active connection with said wafer handling device in said chamber;

transferring wafers to and from a measuring station with the wafer-handling device, the measuring station connected to the chamber; and

employing said wafer-handling device to sort the wafers by transferring wafers directly between the first cassette and the second cassette, wherein the chamber is sealed.

14. (Previously Presented) The method of Claim 13, further comprising the step of testing the wafers during sorting the wafers.

15. (Previously Presented) A method for assembling a batch of wafers in cassettes comprising the steps of:

placing at least a first and a second closed cassette in a store;

employing a cassette handling device to select and move a first cassette from the store to a first closable opening in a sealed chamber;

opening said first closable opening together with said first cassette;

employing a cassette handling device to select and move a second cassette from the store to a second closable opening in said sealed chamber;

opening said second closable opening together with said second cassette; and

employing a wafer-handling device, provided in said sealed chamber, to transfer wafers to and from a measuring station communicating with said sealed chamber and to sort the wafers by transferring wafers directly between the first cassette and the second cassette.